

P-Channel 40 V (D-S) MOSFET

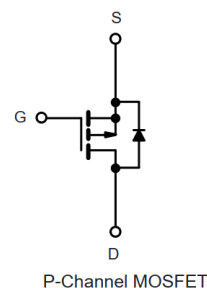
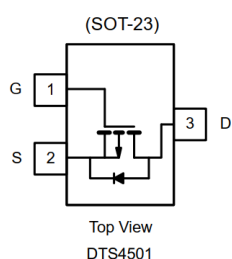

RoHS
 COMPLIANT

PRODUCT SUMMARY

V_{DS} (V)	- 40
$R_{DS(on)}$ (m Ω) at $V_{GS} = -10$ V	83
$R_{DS(on)}$ (m Ω) at $V_{GS} = -4.5$ V	95
I_D (A)	- 3.6
Configuration	Single

FEATURES

- DT-Trench Power MOSFET
- AEC-Q101 Qualified^c
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	- 40	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	$T_C = 25$ °C	A
		$T_C = 125$ °C	
Continuous Source Current (Diode Conduction)	I_S	- 3.6	
Pulsed Drain Current ^a	I_{DM}	- 18	
Single Pulse Avalanche Current	I_{AS}	- 12	
Single Pulse Avalanche Energy	E_{AS}	7.2	mJ
Maximum Power Dissipation ^a	P_D	$T_C = 25$ °C	W
		$T_C = 125$ °C	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 175	°C

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-Ambient	R_{thJA}	166	°C/W
Junction-to-Foot (Drain)	R_{thJF}	50	

Notes

- Pulse test; pulse width 300 μ s, duty cycle 2 %.
- When mounted on 1" square PCB (FR-4 material).

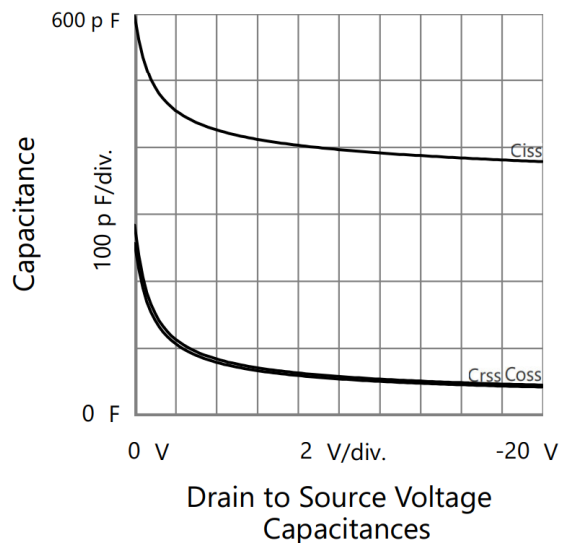
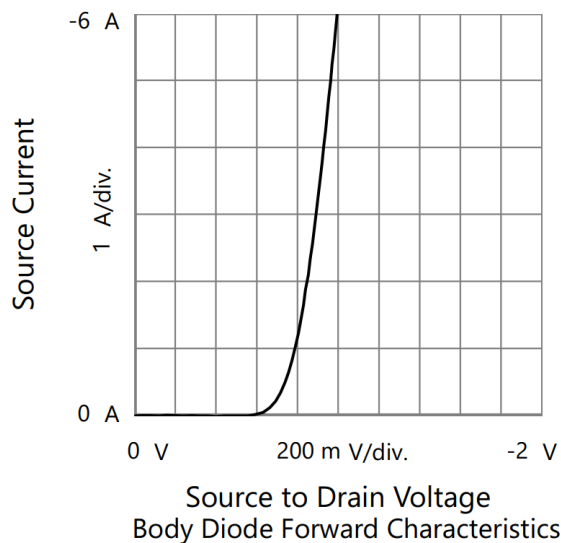
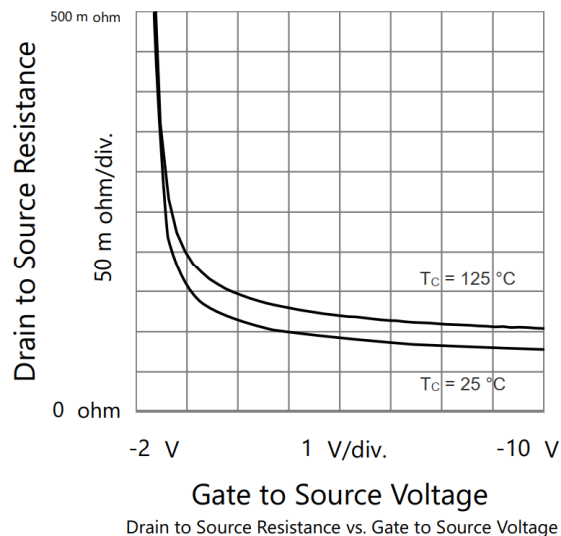
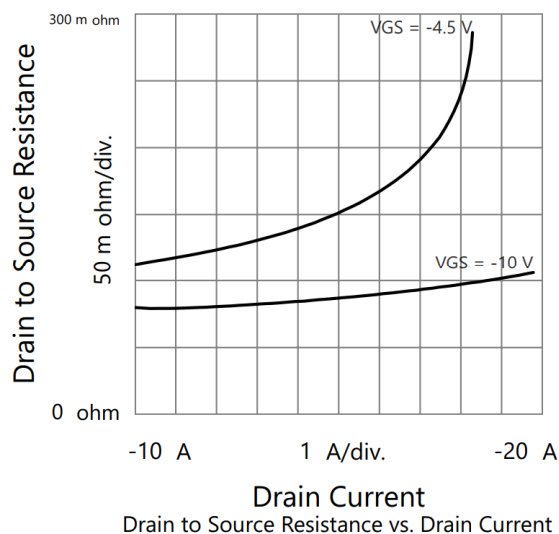
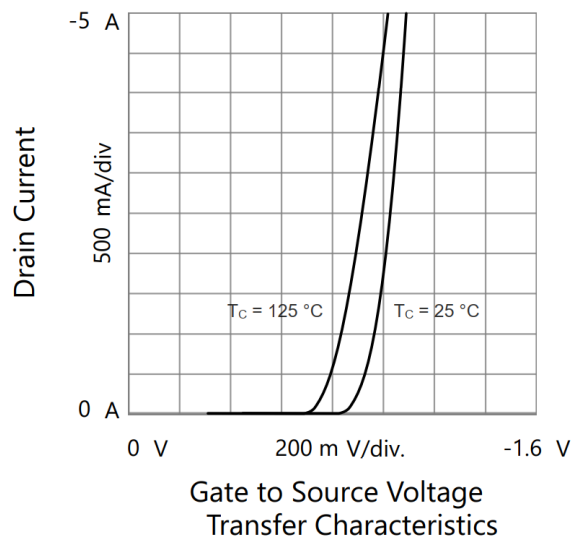
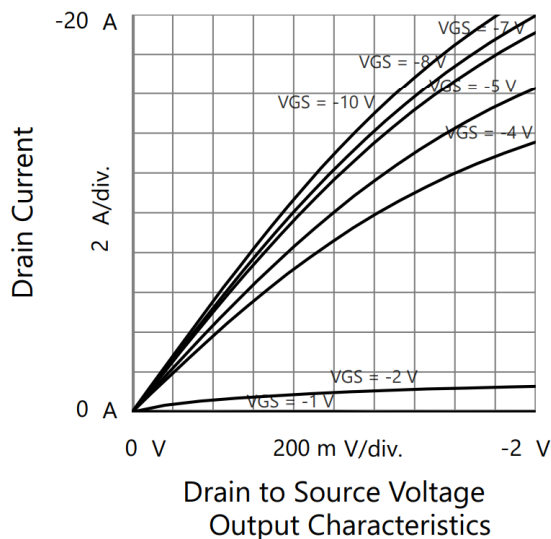
SPECIFICATIONS (T _C = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0, I _D = - 250 μA		- 40	-	-	V
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA		- 1.0	-	- 2.5	
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V	V _{DS} = - 40 V	-	-	- 1	μA
		V _{GS} = 0 V	V _{DS} = - 40 V, T _J = 125 °C	-	-	- 50	
		V _{GS} = 0 V	V _{DS} = - 32 V, T _J = 175 °C	-	-	- 150	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = - 10 V	V _{DS} ≤ - 5 V	- 10	-	-	A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 10 V	I _D = - 3 A	-	83	92	mΩ
		V _{GS} = - 10 V	I _D = - 3 A, T _J = 125 °C	-	110	121	
		V _{GS} = - 10 V	I _D = - 3 A, T _J = 175 °C	-	120	139	
		V _{GS} = - 4.5 V	I _D = - 2.4 A	-	100	110	
Forward Transconductance ^b	g _{fs}	V _{DS} = - 5 V, I _D = - 3 A		-	8	-	S
Dynamic ^b							
Input Capacitance	C _{iss}	V _{GS} = 0 V	V _{DS} = - 25 V, f = 1 MHz	-	682	-	pF
Output Capacitance	C _{oss}			-	448	-	
Reverse Transfer Capacitance	C _{rss}			-	353	-	
Total Gate Charge ^c	Q _g	V _{GS} = - 10 V	V _{DS} = - 20 V, I _D = - 3 A	-	10.5	16	nC
Gate-Source Charge ^c	Q _{gs}			-	1.8	-	
Gate-Drain Charge ^c	Q _{gd}			-	2.6	-	
Gate Resistance	R _g	f = 1 MHz		-	20	-	Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = - 20 V, R _L = 6.7 Ω I _D ≅ - 3 A, V _{GEN} = - 10 V, R _g = 1 Ω		-	5	8	ns
Rise Time ^c	t _r			-	11	17	
Turn-Off Delay Time ^c	t _{d(off)}			-	19	29	
Fall Time ^c	t _f			-	8	12	
Source-Drain Diode Ratings and Characteristics ^b							
Pulsed Current ^a	I _{SM}			-	-	- 18	A
Forward Voltage	V _{SD}	I _F = - 1.5 A, V _{GS} = 0		-	- 0.8	- 1.2	V

Notes

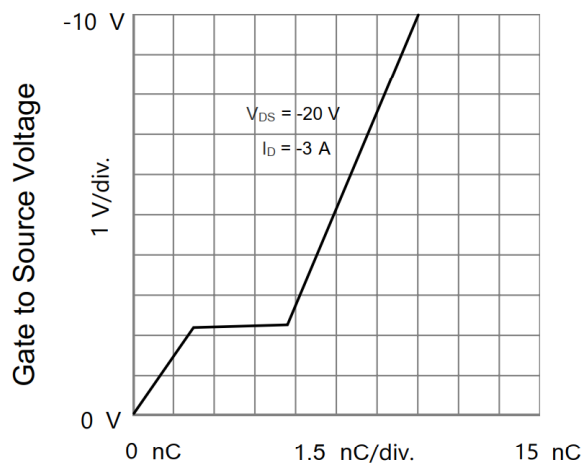
- Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

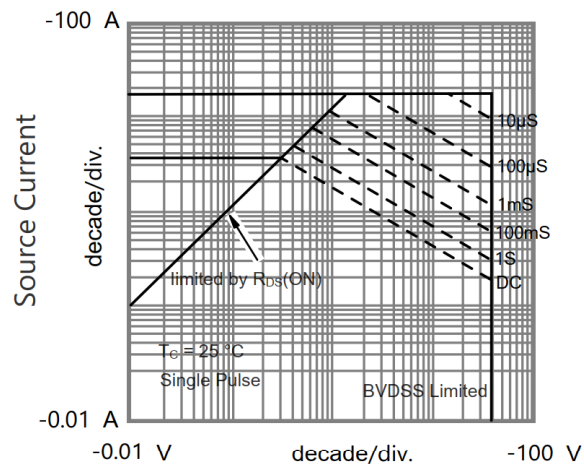
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



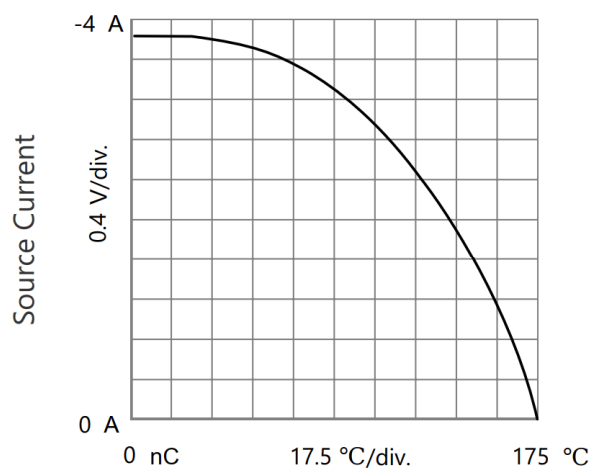
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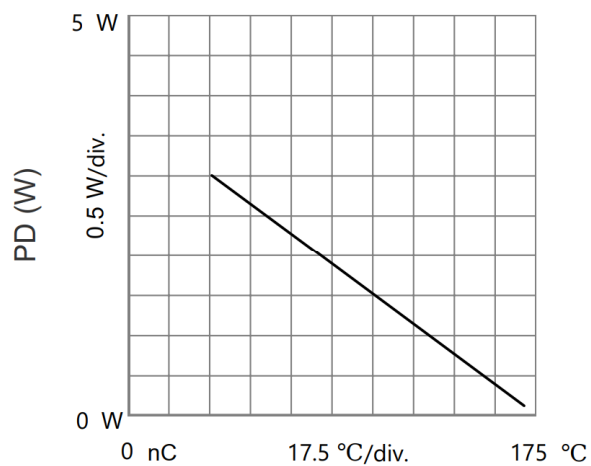
Gate to Source Voltage vs. Gate Charge



Source to Drain Voltage
Safe Operating Area, Junction-to-Ambient

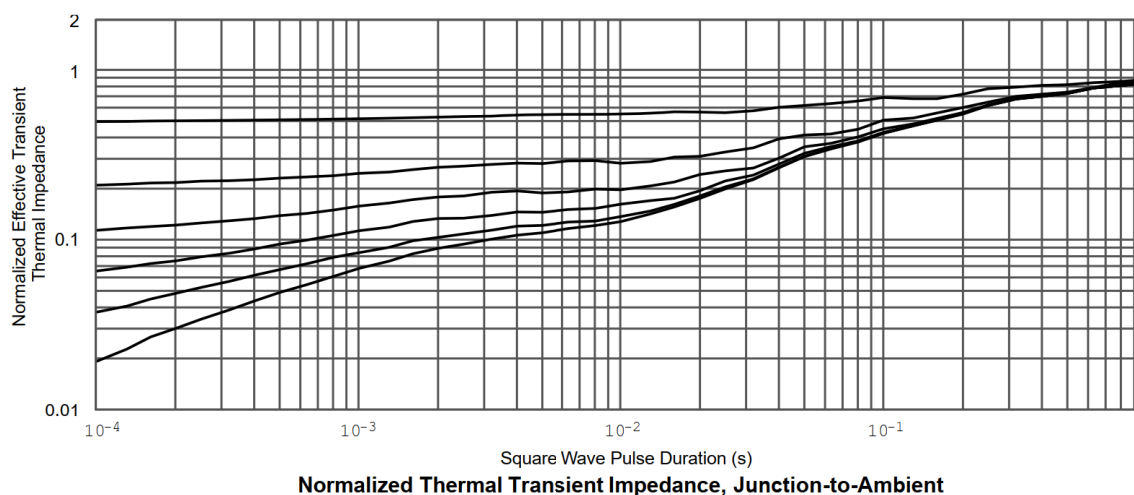


T_C - Case Temperature
Current Derating



T_C - Case Temperature
Power Derating

THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

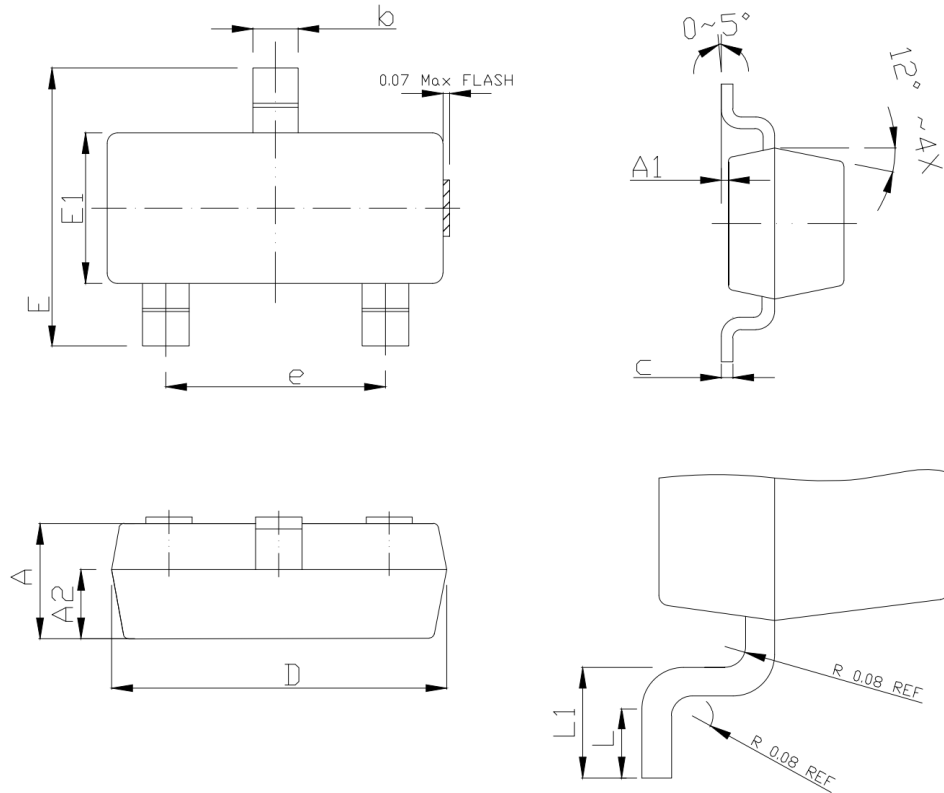


Normalized Thermal Transient Impedance, Junction-to-Ambient

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient ($25\text{ }^{\circ}\text{C}$)
 - Normalized Transient Thermal Impedance Junction-to-Foot ($25\text{ }^{\circ}\text{C}$)
- are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

SOT-23 PACKAGE OUTLINE



COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.80	1.00	1.30
A1	0.00	0.05	0.15
b	0.25	0.40	0.55
c	0.11 BSC		
D	2.60	2.90	3.20
E	2.10	2.40	2.70
E1	1.10	1.30	1.48
e	1.90 BSC		
L	0.17	—	—
L1	0.28	0.40	0.53
A2	0.60 REF		

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